

# NZL5V6AXV3T1 Series

Preferred Devices

## Dual Common Anode ESD Protection Diodes

### SC-89 Package

These dual monolithic silicon ESD protection diodes are intended for use in voltage- and ESD-sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. Their dual junction common anode design protects two separate lines using only one package. These devices are ideal for situations where board space is at a premium.

#### Specification Features:

- SC-89 Package Allows Either Two Separate Unidirectional Configurations or a Single Bidirectional Configuration
- ESD Rating of Class N (exceeding 16 kV) per the Human Body Model
- Meets IEC61000-4-2 Level 4
- Low Leakage < 5.0  $\mu$ A
- These are Pb-Free Devices

#### Mechanical Characteristics:

**CASE:** Void-free, Transfer-molded, Thermosetting Plastic Epoxy Meets UL 94, V-0

**LEAD FINISH:** 100% Matte Sn (Tin)

**MOUNTING POSITION:** Any

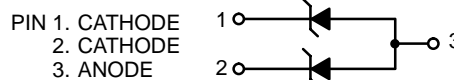
**QUALIFIED MAX REFLOW TEMPERATURE:**

260°C Device Meets MSL 1 Requirements



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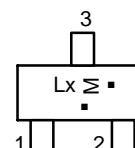
<http://onsemi.com>



#### MARKING DIAGRAM



SC-89  
CASE 463C  
STYLE 4



L = Device Code  
x = Specific Device  
M = Date Code  
■ = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

Device	Package	Shipping†
NZL5V6AXV3T1	SC-89*	3000/Tape & Reel
NZL5V6AXV3T1G	SC-89*	3000/Tape & Reel
NZL6V8AXV3T1	SC-89*	3000/Tape & Reel
NZL6V8AXV3T1G	SC-89*	3000/Tape & Reel
NZL6V8AXV3T3G	SC-89*	10000/Tape & Reel
NZL7V5AXV3T1	SC-89*	3000/Tape & Reel
NZL7V5AXV3T1G	SC-89*	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

\*This package is inherently Pb-Free.

#### DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the table on page 2 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

# NZL5V6AXV3T1 Series

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Total Power Dissipation on FR-5 Board (Note 1) @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	240 1.9	mW mW/ $^\circ\text{C}$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	525	$^\circ\text{C/W}$
Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$
Lead Solder Temperature – Maximum (10 Second Duration)	$T_L$	260	$^\circ\text{C}$
IEC61000-4-2 (Contact)		10	kV

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 board with minimum recommended mounting pad.

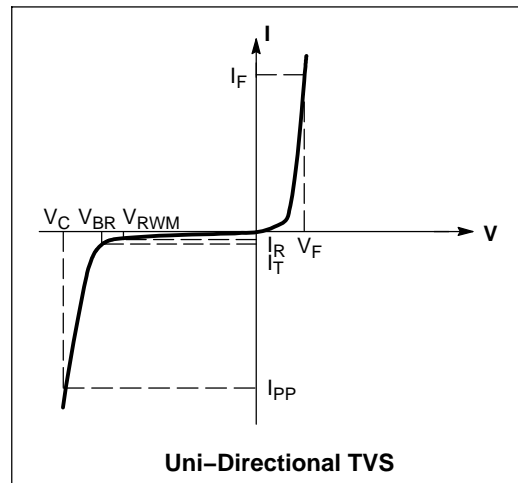
\*Other voltages may be available upon request.

## ELECTRICAL CHARACTERISTICS

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

**UNIDIRECTIONAL** (Circuit tied to Pins 1 and 3 or 2 and 3)

Symbol	Parameter
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current
$I_F$	Forward Current
$V_F$	Forward Voltage @ $I_F$



**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted,  $V_F = 0.9\text{ V Max}$  @  $I_F = 10\text{ mA}$  for all types)

**UNIDIRECTIONAL** (Circuit tied to Pins 1 and 3 or Pins 2 and 3)

Device	Device Marking	$V_{RWM}$ V	$I_R$ @ $V_{RWM}$ $\mu\text{A}$	Breakdown Voltage				Surge			
				$V_{BR}$ (Note 2) (V)			@ $I_{zT}$ mA	$V_C$ (V) @ $I_{PP} = 1.0\text{ A}^\dagger$ Typ	$V_C$ (V) @ $\text{Max } I_{PP}^\dagger$ Max	Max $I_{PP}$ (A) $^\dagger$	$P_{pk}$ (W) $^\dagger$ Typ
				Min	Nom	Max					
NZL5V6AXV3T1	L0	3.0	5.0	5.32	5.6	5.88	5.0	7.0	10.1	4.8	50
NZL6V8AXV3T1	L2	4.5	1.0	6.46	6.8	7.14	5.0	7.9	11.9	6.7	73
NZL6V8AXV3T3	L2	4.5	1.0	6.46	6.8	7.14	5.0	7.9	11.9	6.7	73
NZL7V5AXV3T1	L3	5.0	1.0	7.12	7.5	7.88	5.0	8.8	13.5	5.7	75

2.  $V_{BR}$  measured at pulse test current  $I_T$  at an ambient temperature of  $25^\circ\text{C}$ .

$^\dagger$  Surge current waveform per Figure 5.

# NZL5V6AXV3T1 Series

## TYPICAL CHARACTERISTICS

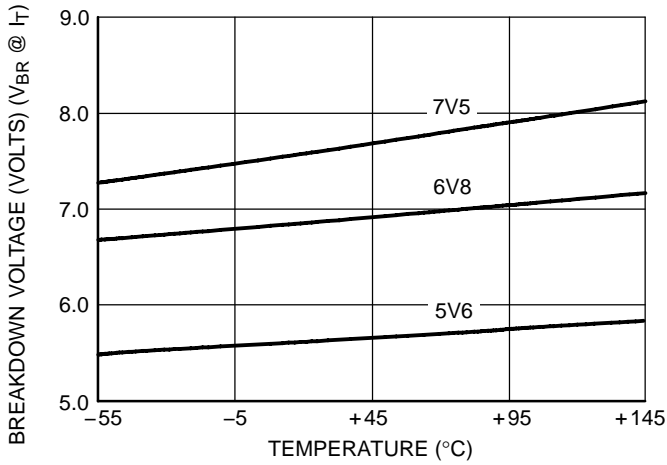


Figure 1. Typical Breakdown Voltage versus Temperature

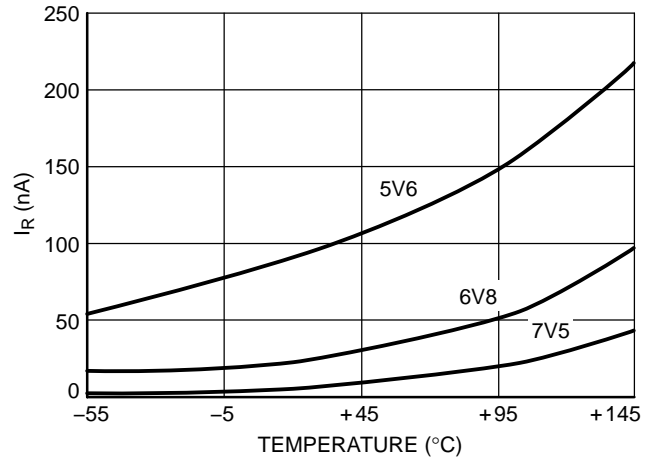


Figure 2. Typical Leakage Current versus Temperature

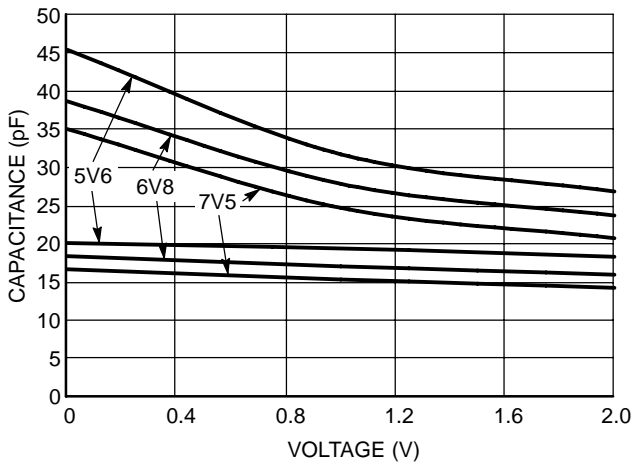


Figure 3. Typical Capacitance versus Bias Voltage  
(Upper curve for each part is unidirectional mode, lower curve is bidirectional mode)

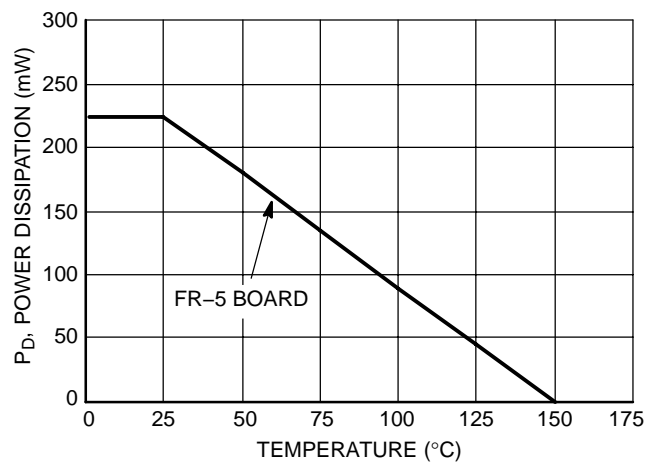


Figure 4. Steady State Power Derating Curve

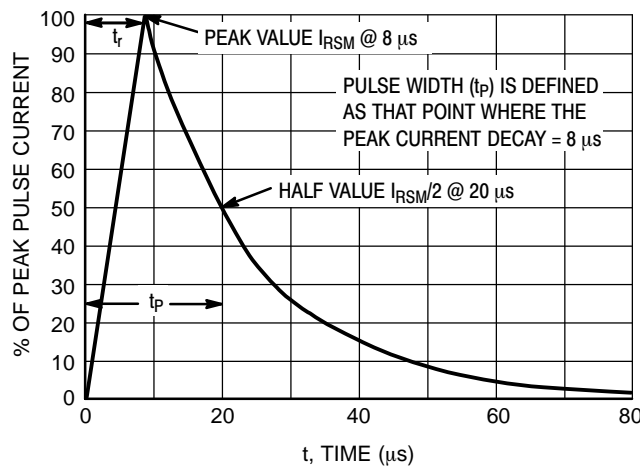


Figure 5. 8 X 20 μs Pulse Waveform

# NZL5V6AXV3T1 Series

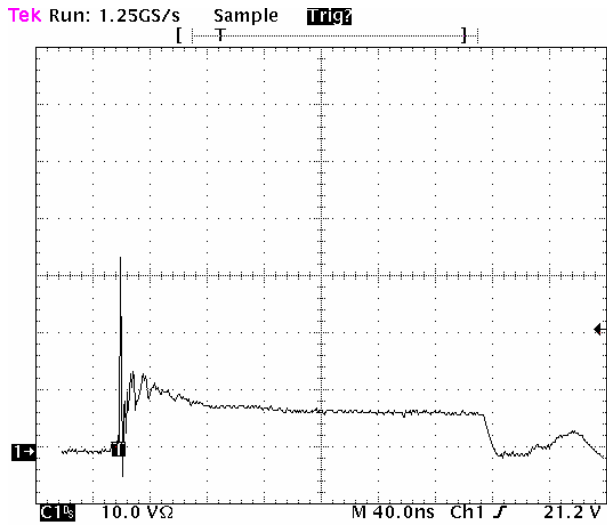


Figure 6. Positive 8 kV contact per IEC 6100-4-2  
- NZL6V8AXV3T1G

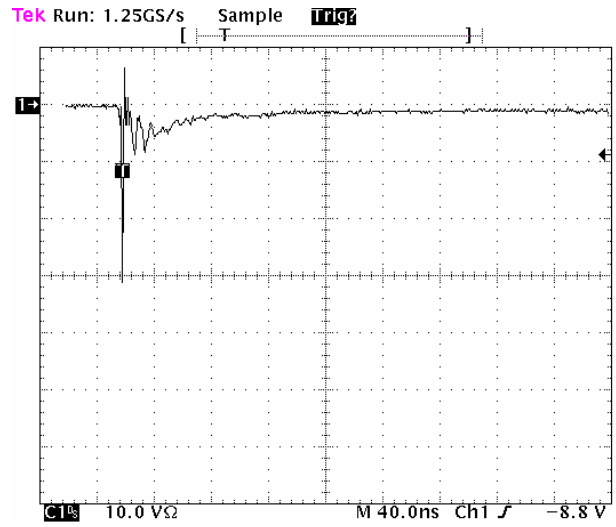


Figure 7. Negative 8 kV contact per IEC 6100-4-2  
- NZL6V8AXV3T1G

# NZL5V6AXV3T1 Series

## TYPICAL COMMON ANODE APPLICATIONS

A dual junction common anode design in an SC-89 package protects two separate lines using only one package. This adds flexibility and creativity to PCB design especially

when board space is at a premium. Two simplified examples of TVS applications are illustrated below.

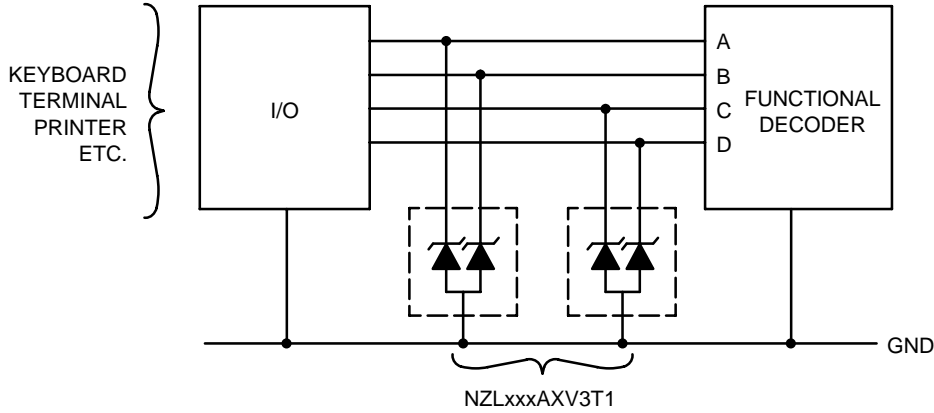


Figure 8. Computer Interface Protection

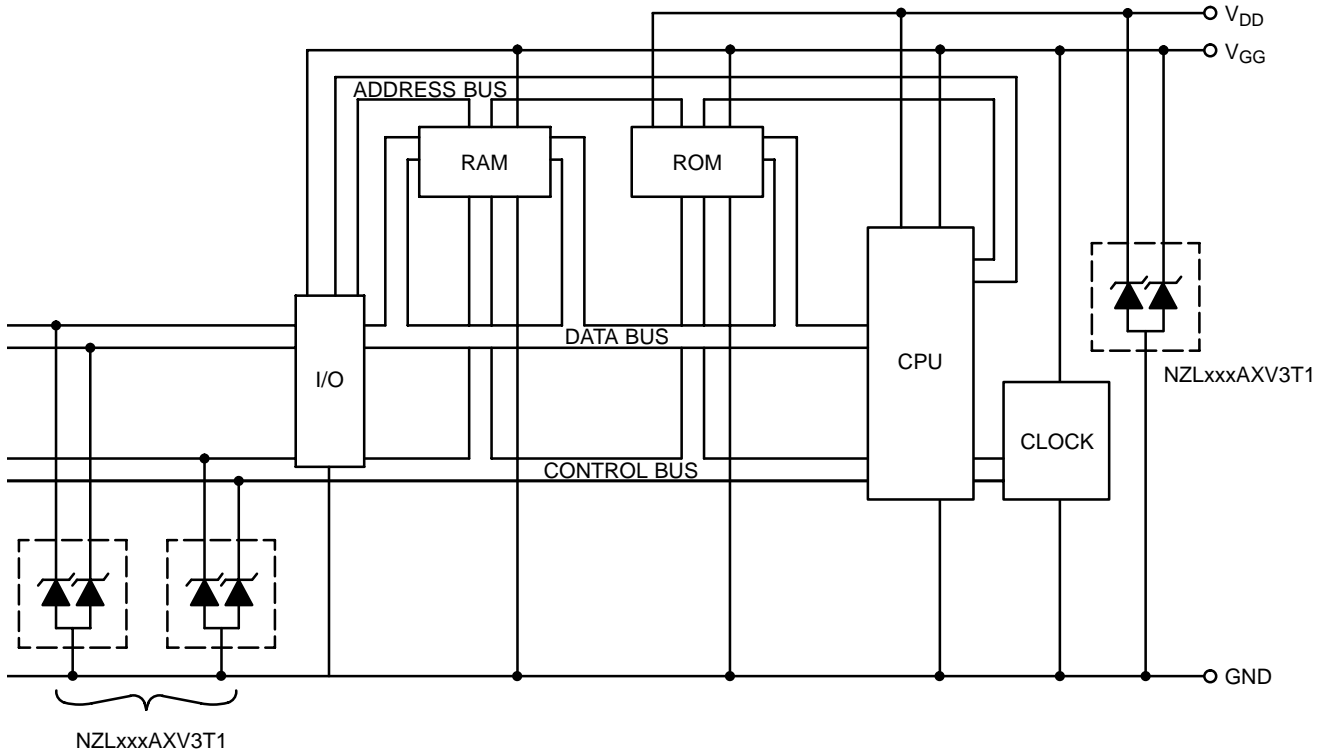
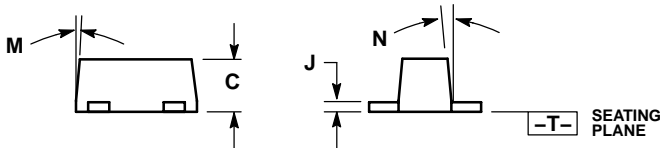
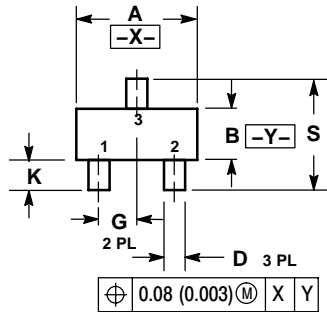


Figure 9. Microprocessor Protection

# NZL5V6AXV3T1 Series

## PACKAGE DIMENSIONS

SC-89, 3-LEAD  
CASE 463C-03  
ISSUE C



NOTES:

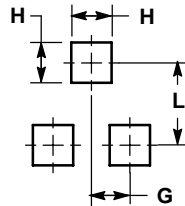
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 463C-01 OBSOLETE, NEW STANDARD 463C-02.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.60	1.70	0.059	0.063	0.067
B	0.75	0.85	0.95	0.030	0.034	0.040
C	0.60	0.70	0.80	0.024	0.028	0.031
D	0.23	0.28	0.33	0.009	0.011	0.013
G	0.50 BSC			0.020 BSC		
H	0.53 REF			0.021 REF		
J	0.10	0.15	0.20	0.004	0.006	0.008
K	0.30	0.40	0.50	0.012	0.016	0.020
L	1.10 REF			0.043 REF		
M	---	---	10	---	---	10
N	---	---	10	---	---	10
S	1.50	1.60	1.70	0.059	0.063	0.067

STYLE 4:

1. CATHODE
2. CATHODE
3. ANODE

### SOLDERING FOOTPRINT



### RECOMMENDED PATTERN OF SOLDER PADS

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#### Как с нами связаться

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